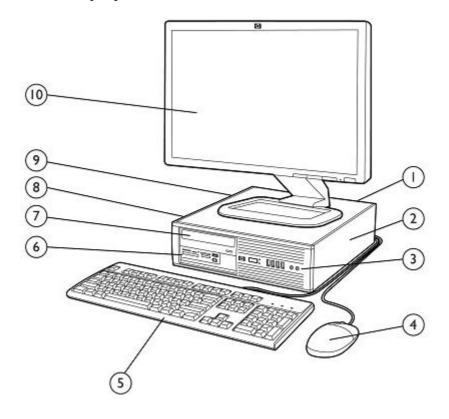
Overview

HP Compaq 8100 Elite Small Form Factor Business PC

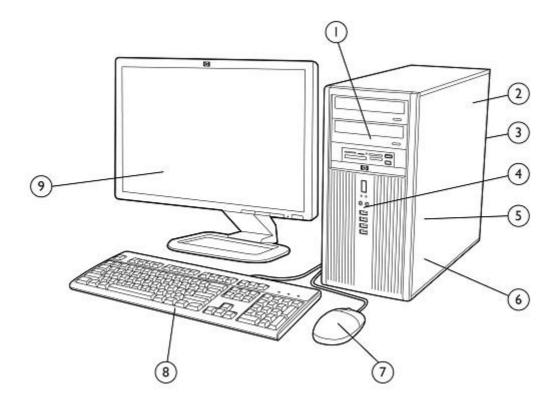


- Rear I/O includes (6) USB 2.0 ports, serial port, PS/2 mouse and keyboard ports, RJ-45 network interface, DisplayPort and VGA video interfaces, and audio in/out jacks
- 2 Low profile expansion slots include (1) PCI slot, (1) PCI Express x1 slots and (2) PCI Express x16 graphics slot
- 3 Front I/O includes (4) USB 2.0 ports, dedicated headphone output, and a microphone/headphone jack
- 4 HP Optical Mouse
- 5 HP Keyboard
- 6 3.5" external drive bay supporting a media card reader or a secondary hard disk drive
- 7 5.25" external drive bay supporting an optical disk drive
- 8 3.5" internal drive bay supporting primary hard disk drive
- 9 240W standard or 89% high efficiency Power Supply
- 10 HP Monitor (sold separately)



Overview

HP Compaq 8100 Elite Convertible Minitower Business PC



- 1 (3) 5.25" external drive bays supporting optical disk drives, removable hard disk drives, or the HP Media Card Reader
- 2 320W standard or 89% high efficiency Power Supply
- Rear I/O includes (6) USB 2.0 ports, serial port, PS/2 mouse and keyboard ports, RJ-45 network interface, DisplayPort and VGA video interfaces, and audio in/out jacks
- 4 Front I/O includes (4) USB 2.0 ports, dedicated headphone output, and a microphone/headphone jack
- 5 (3) 3.5" internal drive bays supporting multiple hard disk drives
- Full height expansion slots include (3) full-length PCI slots, (1) PCI Express x1 slot, and (2) full-length PCI Express x16 graphics slots

NOTE: Second PCIe x16 slot has x4 connectivity.

- 7 HP Optical Mouse
- 8 HP Keyboard
- 9 HP Monitor (sold separately)



Overview

At A Glance

- Designed for long-term deployment within corporate, enterprise, public sector and mid-market commercial organizations
- Choice of two professional chassis form factors to accommodate any desired mix between expandability and size
- BIOS developed and engineered by HP for better security, manageability and software image stability
- Intel® Q57 Express chipset
- DDR3 Synchronous Dynamic Random Access Memory (SDRAM)
- Intel® Core Processors with vPro Technology (requires select processors)
- Supports industry standard management protocols including Intel Standard Manageability and DASH 1.1 (via optional Broadcom NIC card)
- Integrated dual independent monitor support via both a VGA and DisplayPort video interface
- Standard efficiency or 89% high efficiency energy saving power supplies available
- ENERGY STAR qualified models available (dependent upon the desired configuration)
- Models can be configured with multiple hard disk drives in a RAID array
- Guaranteed lengthy purchase lifecycles and image stability
- Software image fully compatible across all models and form factors
- Created using industry leading Design for Environment standards
- Selected configurations with global availability easily set up and ordered through HP.com Business to Business portals (http://h10019.www1.hp.com/business-site/index.html)
- Tailored HP Factory Express deployment and lifecycle services available (http://h71028.www7.hp.com/enterprise/cache/97688-0-0-225-121.aspx)
- Protected by HP Services, including standard warranties up to 5-5-5 (terms and conditions vary by country; certain restrictions and exclusions apply)
- Tool-less serviceability features for easier upgrades and repairs



Standard Features and Configurable Components (availability may vary by country)

Operating Systems

Preinstalled Genuine Windows 7 Home Basic Edition (32-bit)²

Genuine Windows 7 Home Premium Edition (32-bit or 64-bit)² Genuine Windows 7 Professional Edition (32-bit or 64-bit)²

FreeDOS

Supported Genuine Windows Vista Enterprise Edition¹

Genuine Windows Vista Business (32-bit)¹ Genuine Windows Vista Home Basic¹ Genuine Windows 7 Enterprise Edition² Genuine Windows 7 Ultimate Edition²

Certified Novell SUSE Linux Enterprise Desktop 11³

Red Hat Enterprise Linux 643

¹ Certain Windows Vista product features require advanced or additional hardware. See www.microsoft.com/windowsvista/getready/hardwarereqs.mspx and www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: www.windowsvista.com/upgradeadvisor

² System may require upgraded and/or separately purchased hardware and/or a DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See http://www.microsoft.com/windows/windows-7/ for details.

³ The following features are not supported on Linux certified systems:

- HP 22-in-1 media card reader
- Trusted Platform Module (TPM) 1.2 Security Chip
- Intel Pro 1000 CT GbE NIC
- Broadcom NetXtreme GbE Ethernet Plus NIC
- HP 802.11b/g/n wireless NIC (SFF and MT)
- Intel WiFi Link 5100 a/b/g/n wireless NIC (USDT)
- LSI 56K Int'l SoftModem
- HP USB Smartcard keyboard
- HP Serial port adapter
- HP Parallel port adapter
- HP eSATA port adapter
- HP FireWire/IEEE 1394 I/O card



Standard Features and Configurable Components (availability may vary by country)

Value Added Software (included with all models; not included when configured with FreeDOS)

HP ProtectTools Security Suite
HP Software Management Agent
Computrace for Desktops agent (optional)

HP Insight Diagnostics PDF Complete

Value Added Software (included with select models; not included when configured with FreeDOS)

Computer Setup Utility Antivirus software* Roxio Creator Business HP Power Manager HP Total Care Advisor Microsoft Office 2010 preloaded (purchase of a Product Key

required to activate a full Office 2010 suite)**

Firefox HP Virtual Browser

Corel WinDVD

HP Client Management Solutions (available for free download from the Internet)

http://www.hp.com/go/easydeploy)

HP Client Automation Starter* HP SoftPaq Download Manager HP Client Catalog for Microsoft SMS HP Systems Software Manager

Value Added Services and Features

HP Stable Platform Program Intel Stable Platform Program Business-to-Business Portals HP Global Series Services Factory Express Deployment and Lifecycle Services

Intel Standard Manageability

Intel Core 2 Processor with vPro Technology
Trusted Platform Module (TPM) v1.2*

Service and Support

On-site warranty and service¹: three year (3/3/3) limited warranty and service offering delivers three years of parts, labor and on-site repair. Response time is next business day² and includes free telephone support³ 24 x 7. Global coverage² ensures any product purchased in one country and transferred to another non-restricted country will remain fully covered under the original warranty and service offering. Some countries/regions do not offer one year onsite and labor.



^{*} May be Norton or McAfee antivirus software. First 60 days included. Subscription required for live updates thereafter. Internet access required.

^{**} Microsoft Office 2010 Preloaded includes reduced functionality versions of Word and Excel. Purchase of Product Key required to activate full Office 2010 suite available at participating resellers/retailers and http://www.office.com.

^{*} Available from your HP Sales Representative or HP Channel Partner

¹ Terms and conditions may vary by country. Certain restrictions and exclusions apply.

² On-site services may be provided pursuant to a service contract between HP and an authorized HP third party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

³ Technical telephone support applies only to HP configured, HP and HP qualified third party hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

Standard Features and Configurable Components (availability may vary by country)

Chipset

Intel Q57 Express

Processors

NOTE: all models configured with Intel® Core™ processors with 4 cores require a discrete graphics solution

Intel Pentium Processors:

Intel Pentium G6950 Processor 2.80 GHz, 3M total cache

2 cores/2 threads Integrated Intel® HD Graphics

Intel Core i3 Processors:

Intel Core i3-530 Processor 2.93 GHz, 4M total cache 2 cores/4 threads

Integrated Intel® HD Graphics

Intel Core i3-540 Processor 3.06 GHz, 4M total cache

2 cores/4 threads

Integrated Intel® HD Graphics

Intel Core i3-550 Processor

3.20 GHz, 4M total cache

2 cores/4 threads

Integrated Intel® HD Graphics

Intel Core i3-560 Processor

3.33 GHz, 4M total cache

2 cores/4 threads

Integrated Intel® HD Graphics

Intel Core i5 Processors:

Intel Core i5-650 Processor

3.2 GHz, 4M total cache

2 cores/4 threads

Integrated Intel® HD Graphics

Intel® Core™ processor with vPro™ technology

Intel® Stable Image Platform Program (SIPP)

Intel Core i5-660 Processor

3.33 GHz, 4M total cache

2 cores/4 threads

Integrated Intel® HD Graphics

Intel® Core™ processor with vPro™ technology

Intel® Stable Image Platform Program (SIPP)

Intel Core i5-670 Processor

3.46 GHz, 4M total cache

2 cores/4 threads

Integrated Intel® HD Graphics

Intel® Core™ processor with vPro™ technology

Intel® Stable Image Platform Program (SIPP)



Standard Features and Configurable Components (availability may vary by country)

Intel Core i5-680 Processor

3.60 GHz, 4M total cache

2 cores/4 threads

Integrated Intel® HD Graphics

Intel® Core™ processor with vPro™ technology

Intel® Stable Image Platform Program (SIPP)

Intel Core i5-750 Processor

2.66 GHz, 8M total cache

4 cores/4 threads

Requires a discrete graphics solution

Intel Core i5-760 Processor

2.80 GHz, 8M total cache

4 cores/4 threads

Requires a discrete graphics solution

Intel Core i7 Processors:

Intel Core i7-860 Processor

2.80 GHz, 8M total cache

4 cores/8 threads

Requires a discrete graphics solution

Intel® Core™ processor with vPro™ technology

Intel® Stable Image Platform Program (SIPP)

Intel Core i7-870 Processor

2.93 GHz, 8M total cache

4 cores/8 threads

Requires a discrete graphics solution

Intel® Core™ processor with vPro™ technology

Intel® Stable Image Platform Program (SIPP)

Intel Core i7-880 Processor

3.06 GHz, 8M total cache

4 cores/8 threads

Requires a discrete graphics solution

Intel® Core™ processor with vPro™ technology

Redundant Array of Independent Drives (RAID)

Flexible implementation:

- DriveLock is supported while in RAID mode. Users can manage the DriveLock password from within F10 Setup. Locked drives will be displayed as such in the RAID option ROM interface.
- Hard drive information can be viewed within F10 Setup while in RAID mode. Previously, the hard drives will not appear in Drive Configuration when switching to RAID mode.
- DPS Self Test can be executed on physical hard drives while in RAID mode.
- The RAID Setup Utility (accessed through CTRL-I) can be protected by the F10 Setup password.

NOTE: RAID 1 is the only RAID configuration offered via factory configurations. The pre-configured systems:

- Are only available on the CMT and SFF form factors. The USDT does not support RAID as it does not allow for more than one hard disk drive.
- Are complete RAID systems and have both drives installed. If the CMT is configured with three hard disk drives, the third drive is



Standard Features and Configurable Components (availability may vary by country)

would be unpartitioned and not part of the RAID array

- Have the necessary Option ROM configuration.
- Are pre-loaded and pre-installed with all required Intel software.
- Include a preinstalled operating system that is mirrored mode out of the box.

Please refer to the HP White Paper titled "Advanced Host Controller Interface (AHCI) and Redundant Array of Independent Disks (RAID) on HP Compag 8000 Elite Series PCs" at: http://www.hp.com for more information and instructions.

DDR3 Synchronous DRAM NON-ECC System Memory

Memory upgrades are accomplished by adding single or multiple DIMMs of the same or varied sizes. This chart does not represent all possible memory configurations. The HP Compaq 8100 Elite Series PCsupports non-ECC DDR3 PC3-10600 (1333 MHz) and PC3-8500 (1066 MHz) memory.

CAUTION: You must shut down the computer and disconnect the power cord before adding or removing memory modules. Regardless of the power-on state, voltage is always supplied to the memory modules as long as the computer is plugged in to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board.

Memory Configurations

Maximum Memory

Supports up to 16 GB of DDR3 SDRAM using DIMM modules. Slot 1 is black and must always be populated. Not all memory configurations possible are represented below.

NOTE

For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system

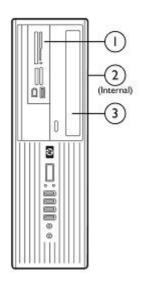
Total Memory	Slot			
	Channel A		Channel B	
	1 (black)	2 (white)	3 (white)	4 (white)
1GB	1 GB			
2 GB (dual channel symmetric)	1 GB		1 GB	
4 GB (dual channel symmetric)	1 GB	1 GB	1 GB	1 GB
8 GB (dual channel symmetric)	2 GB	2 GB	2 GB	2 GB
16 GB (dual channel symmetric)	4 GB	4 GB	4 GB	4 GB

^{*} The Intel Q57 Express chipset includes a built-in Management Engine (ME), which allocates memory for manageability functions. Management Engine memory is shared with system memory. If the PC contains a single S0-DIMM, 16 MB of memory is pre-allocated for it at system startup. If the PC contains two S0-DIMMs, 32 MB of memory is pre-allocated. This memory is not made available to the operating system, just as pre-allocated video memory is not available.

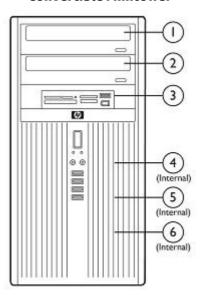


Standard Features and Configurable Components (availability may vary by country)

Small Form Factor



Convertible Minitower



Storage Drive Support						
		Small Form Factor	•	Co	onvertible Minitow	er
	MCR	ODD	HDD SSD	MCR	ODD	HDD SSD
Quantity Supported	1	1	2	1	2	3
Position	1	3	2,1	3	1,2	4,5,6

Data Storage Drives

160-GB Hard Disk Drives

160-GB 3.5" Hard Disk Drive

7,200 rpm, 8MB cache, 3.0 GB/s, NCQ, Smart IV

160-GB 2.5" Hard Disk Drive

10,000 rpm, 16MB cache, 3.0 GB/s, NCQ, Smart III

160-GB Removable Hard Disk Drive

7,200 rpm, 8MB cache, 3.0 GB/s, NCQ, Smart IV

250-GB Hard Disk Drives

250-GB 3.5" Hard Disk Drive

7,200 rpm, 8MB cache, 3.0 GB/s, NCQ, Smart IV

250-GB Removable Hard Disk Drive

7,200 rpm, 8MB cache, 3.0 GB/s, NCQ, Smart IV

320-GB Hard Disk Drives



Standard Features and Configurable Components (availability may vary by country)

320-GB 3.5" Hard Disk Drive

7,200 rpm, 8MB cache, 3.0 GB/s, NCQ, Smart IV

320-GB 2.5" Self Encrypting Hard Disk Drive

7,200 rpm, 8MB cache, 3.0 GB/s, NCQ, Smart IV

320-GB Removable Hard Disk Drive

7,200 rpm, 8MB cache, 3.0 GB/s, NCQ, Smart IV

500-GB Hard Disk Drives

500-GB 3.5"Hard Disk Drive

7,200 rpm, 16MB cache, 3.0 GB/s, NCQ, Smart IV

500-GB Removable Hard Disk Drive

7,200 rpm, 16MB cache, 3.0 GB/s, NCQ, Smart IV

1-TB Hard Disk Drives

1 TB 3.5" Hard Disk Drive

7,200 rpm, 16MB cache, 3.0 GB/s, NCQ, Smart IV

Solid State Drives

64-GB 2.5" Solid State Drive

80-GB 2.5" Solid State Drive

Optical Disc Drives

DVD-ROM Drive¹

SuperMulti DVD Writer Drive 1,2,3

Blu-Ray Writer Drive

¹For playing DVDs, Corel WinDVD 8

²For writing CDs, choice of Sonic/Roxio Easy Media Creator 9 orRoxio Business Creator 10

³For writing CDs and DVDs, video editing and authoring DVDs, choice of Sonic/Roxio Easy Media Creator 9 or Roxio Business Creator 10

Media Card Readers

Media Card Reader (22-in-1)

Media Card Reader (22-in-1) with 1394 port



Standard Features and Configurable Components (availability may vary by country)

Security Solutions and Capabilities

Trusted Platform Module (TPM) 1.21

Stringent Security (via BIOS)2

SATA Port Disablement (via BIOS)

Drive Lock

RAID Configurations

HP ProtectTools Embedded Security Software

Serial, Parallel, USB enable/disable (via BIOS)

Optional USB Port Disable at factory (user configurable via BIOS)

Removable Media Write/Boot Control

Power-On Password (via BIOS)

Setup Password (via BIOS)

Solenoid Hood Lock / Sensor

Support for chassis padlocks and cable lock devices

¹TPM module disabled where use is restricted by law; for example, Russia.

²This setting is defaulted to disable, but when enabled, the PW jumper will not clear the BIOS pre-boot authentication passwords.

Network Interface Connections

Intel 82578 GbE Network Connection (integrated)

Intel Gigabit CT Desktop NIC Card

Broadcom NetXtreme GbE Ethernet Plus NIC (PCIe x1)

HP 802.11 b/g/n Wireless PCIe x1 Card

Note:

The integrated network connection is required to support the vPro Technology features.

Modem

LSI Hi-Speed 56K International Soft Modem (PCIe x1)

Graphics

Intel Graphics Media Accelerator 4500 (integrated)

Nvidia GeForce 310 Card

Nvidia Quadro NVS 290 Card

Nvidia Quadro NVS 295 Card*

ATI Radeon HD 4550 Card

ATI Radeon HD 4650 Graphics Card



Standard Features and Configurable Components (availability may vary by country)

HP DisplayPort to DVI-D Adapter

HP DisplayPort to VGA Adapter

HP DisplayPort to HDMI Adapter

HP DisplayPort Cable

* When ordered with an Nvidia Quadro NVS 295 card, the PC is shipped with two DisplayPort to VGA Adapters. When an Nvidia Quadro NVS 295 card is purchased as an after-market option, it comes with two DisplayPort to DVI-D Adapters.

Audio/Visual

High Definition Audio with Realtek ALC261 codec (all ports are stereo)

Microphone/Headphone* and dedicated headphone front ports

Line-out and Line-In rear Ports*

Multi-streaming capable*

Internal Speaker (standard)

HP Thin USB Powered Speakers

HP TV Tuner

* The front microphone port is re-taskable as a Line-in, Microphone-in or Headphone-in port. Rear audio input ports are re-taskable as a Line-in or Microphone-in port. External speakers must be powered externally. Multi-streaming can be enabled in the Realtek control panel to allow independent audio streams to be sent to/from the front and rear jacks. This allows for different audio applications to use separate audio ports on the system. For example, the front jacks could be used with a headset for a communications application while the rear jacks are being used with external speakers and a multimedia application.

Note: The audio ports/jacks provided by all of our systems are 3.5mm in diameter. This would include both the front jacks and rear jacks, for audio in/out, mic in and headphone out.

Input/Output Devices

PS/2 Standard Keyboard

USB Standard Keyboard

USB CCID SmartCard Keyboard

USB Mini Keyboard

USB and PS/2 Washable Keyboard

PS/2 Optical Scroll Mouse

USB Optical Scroll Mouse

USB Laser Scroll Mouse

USB and PS/2 Washable Mouse

Miscellaneous Devices and Configurations

FireWire (IEEE 1394) Card Serial Port Adapter (RS-232 compatible) Parallel Port Adapter eSATA Port Adapter



Standard Features and Configurable Components (availability may vary by country)

PC Tower Stand
Configure CMT in desktop orientation



After-Market Options (availability may vary by region)

ommunications	SFF	CMT	Part Number
HP Wireless 802.11 b/g/n NIC Card	Χ	Х	FH971AA
Broadcom NetXtreme GbE Ethernet Plus NIC Card	Χ	Χ	FS215AA
Intel Gigabit CT Desktop NIC Card	Χ	Χ	FH969AA
LSI Hi-Speed 56K Int'l Soft Modem Card	Χ	Χ	FH970AA
RJ11 Modem Adapter Kit	Χ	Χ	DC131C
NOTE: The use of a NIC Card (wired or wireless) will disable the	vPro Technology features.		

raphics	SFF	CMT	Part Number
ATI Radeon HD 4550 Graphics Card	Х	Χ	AT042AA
ATI Radeon HD 4650 DP (1GB) PCIe x16 Graphics Card		Х	VN566AA
Nvidia Quadro NVS 290 Graphics Card	Χ	Χ	KG748AA
Nvidia Quadro NVS 295 Graphics Card	X	X	FY943AA
Nvidia GeForce 310 DP PCIe x16 Graphics Card	Х	Х	VG885AA
DMS59 DVI Dual-head Connector Cable	Х	Х	DL139A
HP DVI to DVI cable	Χ	X	DC198A
HP DisplayPort To DVI-D adapter	Χ	X	FH973AA
HP DisplayPort To DL DVI-D adapter	Χ	X	NR078AA
HP DisplayPort to VGA Adapter	Χ	X	AS615AA
HP DisplayPort Cable Kit	Х	Х	VN567AA
ard Disk Storage Drives	SFF	СМТ	Part Number
HP 160GB Hard Disk Drive	Х	Χ	PY277AT
HP 250GB Hard Disk Drive	Χ	Χ	PY278AA
HP 320GB Hard Disk Drive	Χ	Χ	FH963AA
HP 500GB Hard Disk Drive	Х	Х	KW347AA
HP 64-GB Solid State Drive	Х	Х	VG679AA
HP 80-GB Solid State Drive	X	Х	BM848AA
HP eSATA Adapter	Х	Х	FH966AA
HP Removable SATA Hard Drive Enclosure (frame & carrier)	Χ	Χ	RY102AA
HP Removable SATA Hard Drive Enclosure (Carrier Only)	Х	Χ	RY103AA



nput Devices	SFF	СМТ	Part Number
- HP PS/2 Standard Keyboard	Х	Х	DT527A
HP USB Standard Keyboard	Х	X	DT528A
HP USB Mini Keyboard	Х	Х	AS601AA
HP USB Gray Keyboard	Х	Χ	DT529A
HP USB SmartCard Keyboard	X	Χ	ED707AA
HP USB Keyboard and Mouse Kit	X	Х	RC465AA
HP USB Washable Keyboard	Х	Х	VF097AA
HP USB and PS/2 Washable Mouse	Χ	Χ	BM866AA
HP USB and PS/2 Washable Keyboard and Mouse Kit	Χ	X	BU207AA
HP PS/2 Optical Scroll Mouse	Х	Х	EY703AA
HP USB Optical Scroll Mouse	Χ	Χ	DC172B
HP USB Laser Mouse	Χ	X	GW405AA
HP USB Travel Mouse	Χ	Χ	GW405AT
HP 2.4GHz Wireless Keyboard and Mouse	Х	Х	NB896AA
System Memory	SFF	СМТ	Part Number
1 GB DIMM	Х	X	AT023AA
2 GB DIMM	Χ	Χ	AT024AA
4 GB DIMM	Χ	X	VH638AA
Multimedia Devices	SFF	СМТ	Part Number
HP Thin USB Powered Speakers	Х	Х	KK912AA
DVD-ROM Drive	Х	Х	AR629AA
SuperMulti Drive	Х	Х	AR630AA
Blu-Ray Writer Drive	Х	Х	AR482AA
Removable Media Storage	SFF	CMT	Part Number
HP USB External Diskette Drive	Х	Х	DC141B
HP Media Card Reader (22-in-1)	X	Х	AR941AA
HP Media Card Reader (22-in-1) with FireWire (IEEE 1394)	Х	Х	AR942AA



fter-Market Options (availability may vary by reg	1011/		
Security Devices	SFF	CMT	Part Number
HP/Kensington MicroSaver Cable Lock	Х	X	PC766A
HP Business PC Security Lock	Х	X	PV606AA
HP SFF Solenoid Lock and Hood Sensor	Х		BP428AA
HP CMT Solenoid Lock and Hood Sensor		X	DE618A
HP SFF Wall Mount/Security Sleeve	Х		VN570AA
IP Client Automation Software	SFF	СМТ	Part Number
HP Client Automation – Standard Edition (single seat)	Х	Χ	T3488AA
HP Client Automation – Standard Edition (10 seats)	Х	Χ	TA599AA
HP Client Automation – Standard Edition (100 seats)	X	X	TA600AA
HP Client Automation – Standard Edition (500 seats)	Х	Х	TA601AA
HP Client Automation – Standard Edition (1,000 seats)	X	X	T3489AA
itands and Accessories	SFF	СМТ	Part Number
HP SFF Tower Stand	Χ		VN569AA
HP Serial Port Adapter (RS-232 compatible)	Χ	X	PA716A
HP Parallel Port Adapter	Χ	X	KD061AA
HP 5.25" Blank Bezel Kit (50 pack)	Χ	Х	DC177B
HP FireWire (IEEE 1394) Card	Χ	Х	PA997A



Technical Specifications

Weights and	Small Form Factor	Convertible Minitower
Dimensions (configured with 1 HDD and 1 ODD)		
Chassis (H x W x D)	3.95 x 13.30 x 14.9 in 100 x 338 x 378.5 mm	17.63 x 7.00 x 17.5 in 447.8 x 177.8 x 444.5 mm
System Volume	782.77 cu in 12.8 L	2160 cu in 35.4 L
Tower Stand (H x W x D)	1.12 x 7.01 x 7.87 in 28.5 x 178 x 200 mm	N/A
Packaging (H x W x D)	9.00 x 19.68 x 23.38 in 228.6 x 499.9 x 593.85 mm	22.64 x 12.72 x 24.41 in 575.0 x 323 x 620 mm
System Weight*	16.72 lbs 7.6 kg	24.54 lbs 11.15 kg
Shipping Weight*	17.86 lbs 8.1 kg	34.0 lbs 15.42 kg
Max Supported Weight (desktop orientation)	77 lb 35 kg	77 lbs 35 kg

I/O Ports

USB 2.0 Front – four (4) ports

Rear - six (6) ports

Serial one RS-232 compatible port standard

second port available optionally

Parallel one port available as an option eSATA one port available as an option

PS/2 color coded support for keyboard (purple) and mouse (green)

Video VGA and DisplayPort provide integrated dual independent monitor support

DVI output available via optional DisplayPort to DVI Adapter

Audio Front – microphone & headphone

Rear – line input (supports microphone or line input), line out

Note:

See Audio/Visual section for information on re-taskable audio ports.

Note:

The audio ports/jacks provided by all of our systems are 3.5mm in diameter. This would include both the front jacks and rear jacks, for audio in/out, mic in and headphone out.

NIC Industry standard RJ-45 port accesses the integrated network interface controller



Technical Specifications

Slots		Small Form Factor	Convertible Minitower
PCI Slot		(1) low profile PCI slot 25W max power	(3) full height PCI slot 25W max. power
PCI Express x16		(2) low profile PCIe x16 graphics slot 35W max power	(2) full height PCIe x16 graphics slots 75W max. power - primary slot 35W max. power - secondary slot
			Note: Secondary slot functions as a x4 slot
PCI Express	x1	(1) low profile PCIe x1 slot	(1) full height PCIe x1 slot
Bays		Small Form Factor	Convertible Minitower
External	3.5"	(1) bay available for Media Card Reader unless	N/A

Controller	Small Form Factor	Convertible Minitower
5.25"	used for a secondary hard drive (1) bay available for Optical Disc Drive 8.19" deep	3 bays Top two bays accept drives up to 8.19" depth Bottom bay accepts drives up to 5.7"depth

Hard Drive Controller

Serial ATA
Supports SATA 1.5-GB/s and 3.0-GB/

SATA Interfaces

(3) common SATA
(1) eSATA

(1) eSATA

Host SATA Controller

(1) low profile PCIe x1 slot

(1) full height PCIe x1 slot

Unit Environment and Operating Conditions

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's recirculated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)*

Non-operating: -22° to 140° F(-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating: 10,000 ft (3048 m) (unpressurized) Non-operating: 30,000 ft (9144 m)



Technical Specifications

*Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Power Supply	Small Form Factor	Convertible Minitower
Standard Efficiency	240W active PFC	320W active PFC
High Efficiency*	240W active PFC 87/89/85% efficient at 20/50/100% load	320W active PFC 87/89/85% efficient at 20/50/100% load
Operating Voltage Range	90 – 264 VAC	90 – 264 VAC
Rated Voltage Range	100 – 240 VAC	100 – 240 VAC
Rated Line Frequency	50/60 Hz	50/60 Hz
Operating Line Frequency Range	47 – 63 Hz	47 – 63 Hz
Rated Input Current	4A	5.5A
Rated Input Current with Energy Efficient* Power Supply	4A	5.5A
Current Leakage (NFPA 99)	< 275 μΑ	< 450 μΑ
Power Supply Fan	92mm variable speed	92mm variable speed
Power Cord Length	6 ft (1.83 m)	6 ft (1.83 m)
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^{*}High efficiency power supply is a requirement for ENERGY STAR qualification in conjunction with a select range of processors and modules

ROM BIOS Information

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Elite PC into the enterprise, such as PXE, remote configuration, remote control, and F10 Setup support for 12 languages.
- Select models feature either Intel Standard Manageability or Core 2 processor with vPro Technology.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Computrace agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so
 component temperatures are managed for high reliability and to assist in operating the HP Business Desktop computer in any
 enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Business Desktop computers, including BIOS updates
 from within DOS (Flashbin), BIOS updates from within Windows (HPQFlash), HP Client Manager, and fail-safe recovery. In
 addition, the HP Business Desktop BIOS Utilities tool enables replicated BIOS setup throughout the Enterprise; it is available
 from within the BIOS software and from the support website.

Additional HP BIOS Features

- Power-On password Helps prevent an unauthorized user from powering on the system.
- Administrator password Also known as the setup password, this helps prevent unauthorized changes to the system



Technical Specifications

configuration. If the administrator password is not known, the BIOS version cannot be changed and changes cannot be made to BIOS settings using F10 setup or under the OS.

- Advanced Configuration and Power Interface (ACPI) Represents a significant innovation in power and configuration
 management, allowing operating systems and applications to manage power based on activity and usage. HP Elite models use
 ACPI to provide power conservation features.
- S5 Max Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 1W is S5 (when turned off). When S5 Max Power Savings feature is enabled power to slots is turned off along with WOL functionality.

Other Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls
 system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state
 without affecting other elements of the system.
- System Management BIOS v2.6
- Intel Wired for Management support; industry wide initiative to make Intel architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - O Number of 1-second red LED blinks followed by a 2-second pause, then repeats:
 - 2 processor thermal protection activated
 - 3 processor not installed
 - 4 power supply failure
 - 5 memory error
 - 6 video error
 - 7 PCA failure (ROM detected failure prior to video)
 - 8 invalid ROM, bootblock recovery mode
 - 9 system not fetching code
 - 10 system hang while loading an option ROM
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software
- 5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal
- Green Pull Tabs, and Quick Release Latches for easy Identification



Technical Specifications

Additional Features	Description
Intel Standard Manageability	 Requires the utilization of the integrated network connection Available with selected processors not part of the Intel Stable Intel Platform Program (SIPP) Intel Advanced Management Technology (AMT) v3.2 Basic PC management capabilities such as asset inventory, HW alerting, SOL/IDE-R, remote configuration, agent presence and system defense. DASH 1.1 compliance. Support for profile updates. Host VPN support for local management VPN tunneling
Intel Core vPro Processor Technology	 Requires the utilization of the integrated network connection Available with selected processors which are part of the Intel Stable Intel Platform Program (SIPP) Intel Advanced Management Technology (AMT) v6.0 Intel Standard Manageability technologies (see above for a list of features) Fast Call for Help – client outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection Audit Logs – policy based log of AMT actions to deter rogue administrator actions Microsoft NAP Support – allows AMT to gain access to a Microsoft NAP enabled 802.1x network 00B to enable 00B SW updates, inventories, remote diagnostics, etc. Remote Scheduled Maintenance – Pre-schedule when the PC connects to the IT or service provider console for maintenance Remote Alerts – automatically alert IT or service provider if issues arise Access Monitor – Provides oversight to support security requirements
DASH 1.1 support (Desktop and Mobile Architecture for System Hardware)	A standards initiative for representing out-of-band management capability for computer systems. It is a secure, web-services based successor to ASF.
ASF 2.0 support (Alert Standard Format)	Industry-standard specification for network alerting in operating system-absent environments
TXT (Trusted Execution Technology) and VT-d (Virtualized devices)	TXT allows for secure management (via TPM) and measured launch of VMM, as well as teardown of secrets in unexpected reset case. TXT support provided in select Intel processors VT-d is a chipset technology that virtualizes directed I/O Together, TXT and VT-d may be used to support verified launch of a known trusted VMM that also may protect VMs from accessing each other's memory.
Computrace	Computrace agent support standard
Towerable Orientation	Product can be oriented as either a desktop or a tower
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Drive Protection System	DPS Access through F10 Setup during Boot A diagnostic hard drive self test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user Running independently of the operating system, it can be accessed through a Windows- based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be



replaced

Technical Specifications

The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures

SMART Technology (Self-Monitoring, Analysis and Reporting Technology)

Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted

SMART I - Drive Failure Prediction

Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count

SMART II - Off-Line Data Collection

By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure

SMART III – Off-Line Read Scanning with

IOEDC: I/O Error Detection Circuitry

Defect Reallocation

Detects errors in Read/Write buffers on HDD cache RAM

SMART IV - End-to-End CRC for hard drives

Interface in F10 setup provides confirmation of SMART IV support.



Technical Specifications - Audio

High Definition Audio

Type Integrated

Realtek 4-channel ALC261 HD Stereo Codec DAC supports 16/20/24-bit PCM format for 4 channel audio solution

Two stereo ADCs support 16/20-bit PCM format

All DACs support independent 44.1k/48k/96kHz sample rate
All ADCs support independent 44.1k/48k/96kHz sample rate

Front microphone-In (150-K ohm Input Impedance

Rear Line-In/Microphone input (150-K ohm Input Impedance, function is configurable by audio

driver)

Rear Line-Out (190 ohms Output Impedance, expects at least a 10-K ohm load)

Audio I/O Ports

Front Headphone-Out (0.5 Ohm Output Impedance, expects at least a 32 ohm load)

Front Microphone/Headphone jack is re-task able to provide Microphone input, line-in or Headphone output to support connecting two headphones to the front of the system. When configured as a second front headphone output, both front headphone outputs are always driven with the same

signal.

Speakers System includes an internal PC speaker rated 1.5W powered by an internal amplifier. External

speakers must be powered externally.

Multi-streaming Capable Multi-streaming can be enabled in the Realtek control panel to allow independent audio streams to

be sent to/from the front and rear jacks.

Analog Audio Yes

HP Thin USB Powered Speakers

On/Off/Volume Controls Right side of right speaker

Power LED Front of right speaker (green)

Frequency Response F0 to 20kHz

Watts 2/3 watt (normal/maximum)

Dimensions/Speaker 5.72 x 3.74 x 0.96 in (H x W x D) 14.52 x 9.50 x 2.45 cm

Net Weight 0.68 lbs 0.31 kg

Color Black

EnvironmentalOperating Temperature: 14° to 104° F
-10° to 40° C
(all conditions non-condensing)

Relative Humidity 40% to 90%

Input Cord: 5.91 ft 1800mm

Speaker Cable Length L-channel Cord: 3.28 ft 1000mm

USB Cord: 5.91 ft 1800mm



Technical Specifications - Communications

Intel 82578 GbE Network Connection (integrated)

Connector RJ-45

Controller Intel 82578 Gigabit platform LAN Connect Networking Controller

Memory 24 KB FIFO packet buffer memory

Data rates supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3 ab and 802.3u compliant

Bus architecture GLCI, LCI interface. Intel specific MAC to PHY interface

Data transfer mode PCIe-like interface for 1000 speed, SMBus interface for lower 10/100 speeds.

Data rates supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3 ab and 802.3u compliant

Data transfer mode At gigabit GLCI (Intel proprietary 802.3 series-based interface) is for Data, LCI (parallel bus) for MDIO,

at 10/100 LCI for both data and MDIO, GLCI is idle.

Hardware certifications FCC B, CE, TUV- cTUVus Mark Canada and United States, TUV- GS Mark for European Union

Power requirement Requires 3.3V & 1.2V.

Power consumption 761 Milliwatts

ACBS Intel Auto Connect Battery Saving feature

Boot ROM support Yes

Network transfer mode Full-duplex

Half-duplex (not supported for the 1000BASE-T transceiver)

10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps

Network transfer rate 100BASE-TX (half-duplex) 100 Mbps

100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Operating temperature 0° to 85° C

Management WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, Advanced cable diagnostic.

Alerting ASF 2.0 support, AMT 3.0 support

Technical Specifications - Communications

Broadcom NetXtreme GbE Ethernet Plus Network Interface Controller

Connector RJ-45

Controller Broadcom 5761 PCI-Express LAN Controller

Memory 8 MB NVRAM serial Flash

Data rates supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802.1Q, 802.2, 802.3, 802.3AB, 802.3u, and 802.3x

Bus architecture PCI-Express

Data path width Single Channel PCI-Express

Data transfer modeBus Master DMA

Hardware certifications FCC class B, Canada and US NRTL Mark, C-Tick for Australia, BSMI for Taiwan, VCCI for Japan, MIC for

Korea, GOST for Russia, UL listed (E212044), European Union Notice (CE 0682)

Power requirement 1.8W @ 3.3V

Boot ROM support Yes

Network transfer mode Full-duplex

Half-duplex (not available for the 1000BASE-T transceiver)

Network transfer rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Operating temperature 32° to 131°F (0° to 55° C)

Environmental Special Section (1997)

Operating humidity 131° F (55° C) with 5% to 95% non-condensing humidity

Dimensions 2.75 in x 4.13 in (7 cm x 10.5 cm), low profile compatible

Operating system driver

support

Windows Vista 32-bit SP1, Windows Vista x64 SP1, Windows XP 32 bit professional

Management capabilities ACPI, WOL and DMI 2.0, PXE 2.0, WfM 2.0, Broadcom mgmt utility, ASF2.0, DASH 1.0 and DASH 1.1

profiles



Technical Specifications - Communications

Intel GbE CT Desktop Network Interface Connection

Connector RJ-45

Controller Intel 82574L Gigabit Ethernet Controller

Memory Integrated Dual 48K configurable transmit receive FIFO Buffers

Data rates supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802,1Q, 802.2, 802.3, 802.3AB and 802.3u compliant, 802.3x flow control

Bus architecture PCI-E 1.0a

Data path width X1, 250 MB/s, Bi-directional interface

Data transfer modeBus-master DMA

Hardware certifications FCC, B, CE, TUV- cTUVus Mark Canada and United States, TUV- GS Mark for European Union

Power requirement Aux 3.3V, 3.0 Watts in 1000base-T and 2.0 Watts in 100Base-T

Boot ROM support Yes

Environmental

10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps

Network transfer rate 100BASE-TX (half-duplex) 100 Mbps

100BASE-TX (full-duplex) 200 Mbps

1000BASE-T (full-duplex) 2000 Mbps (actual rate limited by PCI Bus)

Operating temperature 32° to 131°F (0° to 55° C)

Operating humidity 85% at 131° F (55° C)

Dimensions 4.75 x 2.25 x 0.8 in (12.1 x 5.7 x 2.0 cm)

Management WOL, PXE, DMI, WFM 2.0

HP Wireless Network Connection 802.11 b/g/n

Dimensions (L x H) 3.3 x 4.7 in

8.5 x 12 cm

Weight 0.08 lbs

40 g

ControllerRalink RT2790System interfacePCIExpress x1Network standard802.11 b/g/nFrequency band2.400 - 2.497 GHz

Operating temperature 14° to 149°F, operating (-10° to 65°C, operating)

Storage temperature -40° to 176°F, non-operating (-40° to 80°C, non-operating)

Humidity 10-90% operating

5-95% non-operating

Operating voltage 3.3V +/- 9%

12V +/- 8%

Platform/WLAN Mode Power Consumption

Maximum Power Consumption 10 Watts

Transmit Only 4 Watts maximum averaged power over 1 second



Technical Specifications - Communications

recrimeat Specimeations	Communications			
	Transmit Packet or Active Scanning	1000 mA peak current for 100 micros	econds or longer	
Power consumption	Receive Only Mode or Idle without IEEE PSP mode enabled	3 Watts maximum averaged over 1 se	cond	
	Idle, with IEEE PSP mode enabled	1 1.0 Watts maximum averaged over 1	second	
	Transmit Disabled (turned off in software)	50 mW maximum, averaged over 1 second		
	Platform in S3 or S4 (power removed from Low Profile PCI Express Card)	5 mW maximum, averaged over 1 sec	ond	
	802.11b mode	+19 dBm +/- 1.0 dB maximum		
Output power (approximately)	802.11g mode	+17 dBm +/- 1.0 dB maximum		
	EWC mode	+17 dBm +/- 1.0 dB maximum (total p	ower in all transmit chains)	
	Mode	Data rate	Sensitivity	
	802.11b	1 Mbps	-94 dBm	
	802.11b	11 Mbps	-85 dBm	
	802.11g	6 Mbps	-91 dBm	
	802.11g	18 Mbps	-85 dBm	
	802.11g	48 Mbps	-75 dBm	
Receive sensitivity	802.11g	54 Mbps	-72 dBm	
	EWC (2.4 GHz)	6.5 Mbps	-87 dBm	
	EWC (2.4 GHz)	54 Mbps	-82 dBm	
	EWC (2.4 GHz)	81 Mbps	-78 dBm	
	EWC (2.4 GHz)	162 Mbps	-74 dBm	
	EWC (2.4 GHz)	270 Mbps	-68 dBm	
	EWC (2.4 GHz)	300 Mbps	-64 dBm	
	Data Rate (MCS)	Minimum Thro	ughput	
	1 Mbps (802.11 b)	700 kbps		
	2 Mbps (802.11 b)	1.4 Mbps		
	5.5 Mbps (802.11 b)	3.5 Mbps		
	11 Mbps (802.11 b)	5.9 Mbps	5	
	12 Mbps (802.11 g)	6 Mbps		
	18 Mbps (802.11 g)	9 Mbps		
	24 Mbps (802.11 g)	12 Mbps		
	36 Mbps (802.11 g)	18 Mbps		
	48 Mbps (802.11 g)	21 Mbps		
	54 Mbps (802.11 g)	22.5 Mbp		
	6.5 Mbps (20 MHz EWC)	4.5 Mbps	5	
	13 Mbps (20 MHz EWC)	9 Mbps		



Data transfer rate

19.5 Mbps (20 MHz EWC)

26 Mbps (20 MHz EWC)

39 Mbps (20 MHz EWC)

13.5 Mbps

18 Mbps

27 Mbps

Technical Specifications - Communications

52 Mbps (20 MHz EWC)	36 Mbps
58.5 Mbps (20 MHz EWC)	40 Mbps
65 Mbps (20 MHz EWC)	45 Mbps
78 Mbps (20 MHz EWC)	54 Mbps
104 Mbps (20 MHz EWC)	72 Mbps
117 Mbps (20 MHz EWC)	81 Mbps
130 Mbps (20 MHz EWC)	91 Mbps
13.5 Mbps (40 MHz EWC)	8 Mbps
27 Mbps (40 MHz EWC)	16 Mbps
40.5 Mbps (40 MHz EWC)	24 Mbps
54 Mbps (40 MHz EWC)	32 Mbps
81 Mbps (40 MHz EWC)	48 Mbps
108 Mbps (40 MHz EWC)	64 Mbps
121.5 Mbps (40 MHz EWC)	72 Mbps
135 Mbps (40 MHz EWC)	81 Mbps
T Witi C4 130 E WED	

IEEE and WiFi compliant 64 / 128 bit WEP encryption

AES: CCM

802.1x authentication

Security WPA: 802.1x. WPA-PSK and TKIP

WPA2 certification IEEE 802.11i

Cisco Certified Extensions, all versions through V5

Antenna HP part number 497792-001

Certifications Wi-Fi certified

Certifications for use by

country

United States, Canada, Peru, Taiwan

Intel WiFi Link 5100 a/b/g/n Wireless Network Interface Connection (USDT)

IEEE 802.11a

IEEE 802.11b

IEEE 802.11g

IEEE 802.11n

Wireless LAN Standards

Note:

The specifications for 802.11n draft 2.0 are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11n WLAN devices. In countries where n draft 2.0 is not allowed, this

capability is not enabled.

Wi-Fi certified (802.11a/b/g only)

Interoperability

Cisco Compatible Extensions Program compliant (802.11a/b/g only) with Microsoft Windows Vista

and XP

Tested with wireless access points from several major manufacturers



Technical Specifications - Communications

Frequency Band 2.4 GHz and 5 GHz

Antenna Structure 1 transmit; 2 receive (1x2)

802.11b: 1, 2, 5.5, 11 Mbps

802.11a/g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

Data Rates 802.11n (draft): 66 possible data rates, ranging from 6 Mbps to 300 Mbps, depending on the

combination of Bandwidth, Modulation Coding Scheme, and Guard Interval used, as defined in IEEE

802.11n (draft) specification

Modulation Direct Sequence Spread Spectrum

DBPSK, DQPSK, CCK, OFDM, BPSK, QPSK, 16-QAM, 64-QAM

Supports 64- and 128-bit WEP, WPA, WPA2, hardware-accelerated AES (support for key sizes of 128, 192, and 256 bits), 802.1x authentication types EAP-TLS, EAP-TTLS, PEAP-GTC, PEAP-MSCHAPv2,

LEAP, EAP-FAST

Security
Support for Cisco Security Features (proven compatibility with Cisco Aironet infrastructure products

through the Cisco Compatible Extensions Program Version 4) with Microsoft Windows Vista and XP

only.

Sub-channels Multinational support with frequency bands and channels compliant to local regulations.

Media Access Protocol CSMA/CA (Collision Avoidance) with ACK

Network Architecture Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power (for CCK) 15 dBm

Output Power (for OFDM; power

varies by data rate)

Power Consumption

15 dBm

Transmit: 2.3 Watts (average, with one spatial streams)

Receive: 1.9 Watts (average with two receive chains

Idle mode: 30 mW (average)

Radio off: 20 mW (max)

Power Management ACPI compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ 300 Mbps: -68 dBm, 54 Mbps: -74 dBm, 6 Mbps: -90 dBm

Antenna Connections 3 U.FL type connectors, 50 ohm nominal impedance

802.11 a - Typical (@6 Mbps)

600 feet - Outdoor Open Area

150 feet - Indoor, Office environment

Range 802.11 b - Typical (@1 Mbps) 1200 feet - Outdoor Open Area

300 feet - Indoor, Office environment

802.11 g - Typical (@1 Mbps)

300 feet - Indoor, Office environment

Form Factor PCI-Express MiniCard

Weight 0.013 lb (6 g)

Dimensions 0.19 x 1.2 x 2.0 in (4.75 x 29.85 x 50.8 mm)

Operating Voltage 3.3V +/- 9%, 1.5V +/- 5%

Temperature Operating: 32° to 176° F (0° to 80° C)

Non-operating: -40° to 176° F (-40° to 80° C)

Technical Specifications - Communications

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 90% (non-condensing)

Altitude Operating: 0 to 10,000 ft (3,048 m)
Non-operating: 0 to 50,000 ft (15,240 m)

Microsoft Windows XP

Microsoft Windows Vista

Configuration Utility⁵

- Microsoft Windows XP Wireless Network Connection Manager
- Intel PROSet for Microsoft Windows XP (required for Cisco Compatible Extensions support)
- Microsoft Windows Vista Wireless Network Connection Manager.
- Intel IHV extensions for Windows Vista available to support Cisco Compatible Extensions.
- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. In Power Save Polling mode and on battery power.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CCK modulation) and a packet error rate of 10% for 802.11a/q (OFDM modulation).
- 5. WLAN supplier's client utility is required for Cisco Compatible Extensions support with Microsoft Windows XP. WLAN may also be compatible with certain third-party software supplicants. WLAN supplier IHV extensions required for Cisco Compatible Extensions support for Microsoft Windows Vista.

LSI 56K International SoftModem PCI Express x1 Card

Data Transmission Technology speeds: 56,000 Kbps maximum downstream data, controllerless

Note:

56 Kbps technology refers to download speeds only and requires compatible modems at server sites. Other conditions may limit modem speed. FCC limitations allow a maximum of 53 Kbps during

download transmissions.

Data Speeds (Upload only) 33,600/31,200/28,800/26,400/21,600/19,200/

16,800/14,400/12,000/9,600/7,200/4,800/2,400/1,200/300

Data Standards ITU-T V.90, ITU-T, ITU-T V.34, V.44, V.42, V.42bis21, V.32bis, Bell 212A, and Bell 103

Fax Speeds 14,400/12,000/9,600/7,200/4,800/2,400/1,200/300 b/

Fax Mode Capabilities ITU-T T.31 class 1 FAX, V. 17, V.29, V.27ter, and V.21 Channel 2

Error Correction and Data

Compression

Power Management

V.44, 42bis, V.42 and MNP2-5

PCI Bus Power Management Interface Specification (PCI-PM) Revision 1.2, Appendix A. D0, D3hot, and D3cold. Wake on Ring state when in D3cold. If the power management event (PME) feature is

enabled in D3cold, a modem can wake the system via WAKE# (WAKEN) or beacon. Meets PCI Express

1.1 standard.

Upgradeability Driver upgradeable for future enhancements

Video ITU-T V.80 video ready interface

TIA/EIA 602 standard AT command set

Other Integrated DTE interface with speeds of up to 115.2 Kbps, parallel 16550a UART-compatible

interface

Optional ring wakeup signal

Operating Temperature 32° to 158° F (0° to 70° C)
Operating Humidity 20% to 90%, non-condensing

Technical Specifications - Communications

Power Requires a 3.3-V auxiliary power rail on PCI express bus

Uses only one PCI express load (i.e., one grant/request pair), one shared IRQ, one electrical load

Chipset LSI SV92EX - Integrated PCI interface with 3.3-V tolerant buffers and CardBus support

Dimensions (L X H) Complies with PCI express low profile specifications-6.7 x 2.3 in (17.0 x 5.8 cm) and supports high-

and low-profile brackets

Connection Single RJ-11 connector

Other Features

Digital line protection, call progress monitoring via on-board piezo device, support for high profile

and low profile brackets, PnP ID support

Safety

UL recognized to UL 1950, 3rd edition (U.S. and Canada); IEC 950 (TUV, NEMKO, DEMKO, SEMKO); CE

Mark, EC 950 (TUV, NEMKO, DEMKO, SEMKO, CE mark

EMC FCC Part 15, IC ES003, EN 55022, 3rd edition, EN 55024, annex A, EN 61000-4-6, EN 61000-4-8

Telecom FCC Part 68, IC-CS-03 (Canada); Worldwide PTT approvals

Not available in Korea or the Republic of South Africa.

Other The SV92EX device is packaged in a 32-pin micro leadless chip carrier (MLCC). The SV92EX is fully

compliant with the PCI Express revision 1.1 specification. WHQL approved; ASPM compliant.



Technical Specifications - Graphics

Intel HD Graphics

Memory

3D/2D Controller Microsoft DirectX® 10 based with support for Pixel Shader 3.0

VGA Controller Integrated

DisplayPort Integrated, Multimode capable; supports HDCP

Bus Type PCI Express™ x16 **RAMDAC** Integrated, 350 MHz

Graphics memory is shared with system memory. Graphics memory usage varies depending on the amount of system memory installed, BIOS settings, operating system, and system load. 32 MB is pre-allocated for graphics use at system boot time. Additional memory can be allocated at boot time by the BIOS for PAVP (Protected Audio Video Playback) support for playback of protected video content. For Vista, use of PAVP

heavy mode preallocates an additional 96MB.

Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.

Total System Memory Pre-Allocated (MB) DVMT (MB) .5GB 32 128 Windows XP Memory 1.0GB 32 512 Usage 1.5GB 32 768 2.0GB & more 32 1024

Assumes Management Engine, VT-d enabled and other memory allocated for other BIOS usage

Total Avail Dedicated Shared System Video **Avail System** System **PVAP** GFX Memory Video Memory System Memory (MB) Memory Memory (MB) (MB) (MB) Memory (MB) 124 Lite 952 252 32 96 1 GB 6 294 122 166 Heavy 856 Lite 1976 764 32 96 636 2 GB Heavy 1880 806 122 6 678 Lite 4024 1759 32 96 1631 4 GB Heavy 3928 1759 122 6 1631 Lite 6072 1759 32 96 1631 6 GB Heavy 5976 1759 122 6 1631 Lite 8120 1759 32 96 1631 8 GB Heavy 8024 1759 122 6 1631

HW Video Decode

Hardware Accelerated decode for MPEG2 encrypted video; support for PAVP Lite (default) and Heavy (or Paranoid) modes

Maximum Color Depth 32 bits/pixel

Windows XP Memory

Usage

Maximum Vertical Refresh Rate 85 Hz at up to 1920x1440, 75 Hz at 2048x1536. Varies with mode and configuration. See table below.

Integrated dual independent monitor support facilitated via one VGA port and one DisplayPort integrated on the back plane of the system board and presented as part of the rear I/O set of interfaces. DVI supported with a strong I/O set of interfaces. DVI supported to DVI DisplayPort to DVI DisplayP

via optional HP DisplayPort to DVI-D adapter.



Technical Specifications - Graphics

Graphics/Video API

Support

Microsoft DirectX® 10, OpenGL® 1.5 (OpenGL® 2.0 available in a driver update)

Maximum	Refres	h Rate ((Hz)
---------	--------	----------	------

Resolutions Supported	Resolution	Analog Connection	Digital Connection
	640x480	85	60
	800x600	85	60
	1024x768	85	60
	1280x720	85	60
	1280x1024	85	60
	1440x900	75	60
	1600x1200	85	60
	1680x1050	75	60
	1920x1080	85	60-R
	1920x1200	85	60-R
	1920x1440	85	N/A
	2048x1536	75	N/A
	2560x1600	N/A	60*

^{*} Only supported when using a DisplayPort connection

Note:

Other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Note:

60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections

NVIDIA Quadro NVS 290 Graphics Card

Bus TypePCI Express x16; low profilePCI Express x1, low profileMemory256 MB 400MHz DDR2 SDRAM unified frame buffer, Z-buffer and Texture storage

ConnectorSingle high-density DMS-59 Flex ConnectorDimensionsLow-profile, 2.586 x 6.6 in (6.57 x 16.76 cm)

Multi-Monitor supportDual monitor supportRAMDACIntegrated dual 400MHz

Maximum Pixel Clock 350-MHz

Overlay planes One 16-bit video overlay plane One 1-bit video overlay plane

Full screen, full frame video playback of HDTV and DVD content

DVD ready motion compensation for MPEG-2

High Definition Video Processor Independent hardware color controls for video overlay Hardware color space conversion (YUV 4:2:2 and 4:2:0)

IDCT motion componention

IDCT motion compensation

5-tap horizontal by 3-tap vertical filtering

8:1 up/down scaling

Specification Description



(HDVP)

Technical Specifications - Graphics

Description G86-825 **Board Configuration** Core Clock 460-MHz

Memory Clock 400-MHz

Frame Buffer 256-MB DDR2, 64-bit wide

Dual integrated analog display controllers supporting up to two analog displays at 2048x1536 @

85Hz on both displays or dual digital displays at 1920x1200 (single-link).

Display resolution support

NVIEW advanced multi-display desktop and application management seamlessly integrated into

Microsoft Windows

Color planes 32-bit color buffer

DVI support DMS-59 (to dual DVI-SL)

Supported graphics APIs OGL 2.1 & DX10 Support; Shader Model 4.0

Maximum Refresh Rate

Resolution	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	N/A

Resolutions Supported

Note:

Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP

Note:

60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections



Technical Specifications - Graphics

NVIDIA Quadro NVS 295 Graphics Card

Form Factor 2.731 inches (H) × 6.600 inches (L), Half-Height

Graphics Controller NVIDIA Quadro NVS 295 Graphics Board

Bus Type PCI Express x16, Generation 2.0

Memory 256 MB GDDR3 SDRAM unified graphics memory

2 DisplayPort

Connectors Comes with 2 DisplayPort to VGA Adapters

Note:

When purchased as an after-market option, this comes instead with 2 DisplayPort to DVI-D adapters.

Maximum Resolution Two DisplayPort outputs drive two digital displays up to 2560 x 1600

Drives DisplayPort enabled digital displays at resolutions up to 2560 x 1600 at 60 Hz with reduced

Display Output blanking

Drives DVI enabled digital displays at resolutions up to 1920 × 1200 at 60 Hz with reduced blanking

(through DisplayPort to DVI-D (single link) cable)

Supported Graphics APIs

OpenGL 3.0

Diversity 10.6

DirectX 10.0

NVIDIA GeForce 310 Graphics Card

Bus type PCI Express (x16 lanes)

Board display

options Supports two displays via the DisplayPort and DVI connectors

Specification Description Description

Graphics Chip RV620

Board Core clock 750 MHz

Memory clock 500 MHz

Frame buffer 512 MB DDR3, 64 bit wide

Audio

Support Integrated HD Audio codec supports linear PCM and Dolby® Digital (7.1) audio formats for HDMI output

(through HDMI only)

Core power 22 W (max)

Dimensions 2.71 in x 6.60 in

(H x D) 68.90 mm x 167.65 mm

Weight 0.30 lb (134.3 g)

Maximum

vertical 85 Hz

refresh rate

Display

support

ienesinate

Integrated 400 MHz RAMDAC

Display max

resolution 2560 x 1600 digital, 2048 x 1536 analog



Tochnical Specifications - Graphics

	Posalution	Maximum Bafi	Marrianna Defrech Date (U-)		
	Resolution	Maximum Refresh Rate (Hz)			
		Analog Connection	Digital Connection		
Supported Resolutions	640x480	85	60		
	800x600	85	60		
	1024x768	85	60		
	1280x720	85	60		
	1280x1024	85	60		
	1440x900	75	60		
	1600x1200	85	60		
	1680x1050	75	60		
	1920x1080	85	60-R		
	1920x1200	85	60-R		
	1920x1440	85	N/A		
	2048x1536	75	N/A		
	2560x1600	N/A	60*		
	* Only supported when using a dual-link DV	l or DP connection.			
	Note:				
	Other resolutions may be available but are qualified by HP	not recommended as the may not have been te	sted and		
	Note:				
	60-R denotes reduced blanking timings are other digital connections	used on single-link DVI connections and may be	e used with		

other digital connections

NVIDIA GeForce 310 DP PCIe x16 Graphics Cardwith full height bracket attached

Option Kit Contents

DVI to VGA Adapter

Software CD with graphics drivers

Low profile bracket to convert the card for use in a low profile chassis

Warranty documentation

Compliance **Standards**

EMC Emissions EMC Immunity

FCC Part 15, Subpart B - Unintentional Radiators, Class B

Computing Devices for Home & Office Use

CISPR22: 1997/EN 55022:1998 - Class B - Limits and methods of measurement of radio disturbance characteristics of Information

Technology Equipment

Canadian Standard ICES-003 is equivalent to CISPR22

Taiwanese Standard BSMI

Japanese VCCI Australian C-Tick Korean (MIC)

CISPR 24:1997/EN 55024:1998 - Information Technol Equipment - Immunity Characteristics - Limits and Me Measurement



Technical Specifications - Graphics

ATI Radeon HD 4550 Graphics Card

Bus type PCI Express x16

Maximum vertical refresh rate 85 Hz

Display support Integrated 400 MHz RAMDAC

Display max resolution 1900 x 1200 digital, 2048 x 1536 analog

Board display options
Supports two displays via included DMS-59 to dual VGA cable or 2 DVI monitors via optional DMS-59

to dual DVI cable kit part number: DL139A. 4-pin mini-DIN S-video connector for TV output

Specification Description

Graphics Chip RV710

Board configuration Core clock 600 MHz

Memory clock 800 MHz

Frame buffer 512 MB DDR3, 64 bit wide

24 languages: English, Arabic, Chinese Simplified, Chinese Traditional, Czechoslovakian, Danish, **Languages supported**Dutch, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Korean, Norwegian,

Polish, Portuguese, Russian, Spanish, Swedish, Thai, Turkish

EMC Emissions EMC Immunity

Measurement

FCC Part 15, Subpart B – Unintentional Radiators, Class B Computing Devices for Home

& Office Use

CISPR22: 1997/EN 55022:1998 – Class B – Limits

and methods of measurement of radio disturbance characteristics of Information

Compliance standards Technology Equipment

Canadian Standard ICES-003 is equivalent to

CISPR22

Taiwanese Standard BSMI

Japanese VCCI

Australian C-Tick

Korean (MIC)

CISPR 24:1997/EN 55024:1998 - Information

Technology Equipment – Immunity

Characteristics - Limits and Methods of

Resolutions Supported

Technical Specifications - Graphics

Maximum Refresh Rate (Hz)

	Plaximum Refresh Rate (112)	
Resolution	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	N/A

Note:

Other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Note:

60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections

ATI Radeon HD 4650 Graphics Card

Bus type PCI Express x16

Maximum vertical refresh rate 85 Hz

Display support Integrated 400 MHz RAMDAC

Display max resolution 2560 x 1600 digital, 2048 x 1536 analog



Resolutions Supported

Technical Specifications - Graphics

Maximum Refresh Rate (Hz)

	Maxillulli Kellesii Kate (nz)	
Resolution	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	60*

^{*} Only supported when using a dual-link DVI or DP connection

Note:

Other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Note:

60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections

Board display options

Supports two displays via included two DisplayPort and one Dual Link DVI-I connectors.

Specification Description

Graphics Chip RV635

Board configuration Core clock 725 MHz

Memory clock 500 MHz

Frame buffer 1 GB DDR3, 128 bit wide

Core power 56 W



Board configuration

Technical Specifications - Graphics

Board display options Supports two displays via included two DisplayPort and one Dual Link DVI-I connectors.

EMC Emissions

EMC Immunity

FCC Part 15, Subpart B - Unintentional Radiators, Class B Computing Devices for Home & Office

Use

Technology Equipment - Immunity

CISPR 24:1997/EN 55024:1998 - Information

Characteristics - Limits and Methods of

Measurement

CISPR22: 1997/EN 55022:1998 - Class B - Limits

and methods of measurement of radio disturbance characteristics of Information

Technology Equipment

Canadian Standard ICES-003 is equivalent to

CISPR22

Taiwanese Standard BSMI

Japanese VCCI **Australian C-Tick** Korean (MIC)

HP DisplayPort to DVI-D Adapter

Connectors DisplayPort and DVI-D single link connector

Adapter length 7.5 in (19.0 cm) Adapter weight .10 lbs (.05 kg)

HP DisplayPort to VGA Adapter

Connectors DisplayPort and VGA connector

8 in (20 cm) Adapter

length

Adapter .1 lbs (.06 kg)

weight

Maximum 85 Hz

vertical refresh rate

Display 162 MHz RAMDAC

support

Display 1600x1200

max resolution



Technical Specifications - Graphics

Resolutions	Resolution	Max refresh rate
Supported	640x480	85
	800×600	85
	1024x768	85
	1280x720	85
	1280x1024	85
	1440x900	75
	1600x1200	60
	1680x1050	60
	1920x1080	60-R
	1920x1200	60-R

Note:

Other resolutions may be available but are not recommended as they may not have been tested and qualified by HP. Using t DisplayPort to VGA Adapter may require an update to the graphics driver installed on your system. To install the most up-to graphics driver go to: www.hp.com.

Note:

60-R denotes reduced blanking timings are used. Not all monitors support reduced blanking timing.



Technical Specifications - Hard Drives

160-GB 3.5" Hard Disk Drive

Capacity 160,041,885,696 bytes

Rotational Speed 7,200 rpm

Interface Serial ATA (SATA)

Synchronous Transfer Rate Up to 3 GB/s

(Maximum)

Buffer Size 8 MB

Logical Blocks 312,581,808

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 0.9 ms

Average: 9.3 ms

Height (nominal) 1 in/2.54 cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F

5° to 55° C

250-GB 3.5" Hard Disk Drive

Capacity 250,059,350,016 bytes

Rotational Speed 7,200 rpm

Interface Serial ATA (SATA)

Synchronous Transfer Rate

(Maximum)

Up to 3 GB/s (limited by the system SATA controller)

Full-Stroke: 18 ms

Buffer Size 8 MB

Logical Blocks 488,397,168

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 1.0 ms

Average: 8.5 ms

Full-Stroke: 18 ms

Height (nominal) 1 in/2.54 cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

Technical Specifications - Hard Drives

320-GB 3.5" Hard Disk Drive

Capacity 320,069,031,690 bytes

Rotational Speed 7,200 rpm

Interface Serial ATA (SATA)

Synchronous Transfer Rate Up to 3 GB/s

(Maximum)

Buffer Size 8 MB

Logical Blocks 625,142,448

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 1.0 ms

Average: 8.5 ms

Full-Stroke: 18 ms

Height (nominal) 1 in/2.54 cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

500-GB 3.5" Hard Disk Drive

Capacity 500,107,862,016 bytes

Rotational Speed 7,200 rpm

Interface Serial ATA (SATA)

Synchronous Transfer Rate Up

(Maximum)

Up to 3 GB/s (limited by the system SATA controller)

Buffer Size 16 MB Logical Blocks 976,773,168

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 2.0 ms

Average: 11 ms

Full-Stroke: 21 ms

Height (nominal) 1 in/2.54 cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)



Technical Specifications - Hard Drives

160-GB 10,000 rpm Hard Disk Drive

Capacity 160,041,885,696 bytes

10,000 rpm **Rotational Speed** Interface Serial ATA (SATA)

Synchronous Transfer Rate

(Maximum)

Up to 3 GB/s (limited by the system SATA controller)

Buffer Size 16 MB

Logical Blocks 312,581,808

Seek Time (typical reads, Single Track: 0.3 ms includes controller overhead. Average: 4.6 ms including settling)

Full-Stroke: 10.2 ms

Height (nominal) 1 in/2.54 cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

41° to 131° F **Operating Temperature**

5° to 55° C

64-GB 2.5" Solid State Drive

64 GB Capacity

Interface Serial ATA (SATA)

Architecture Multi Level Cell (MLC) NAND Flash with wear leveling 10 channel controller

Write speed Up to 220 MB/s Internal transfer rate

Read speed Up to 120 MB/s

Host transfer rate Ultra DMA mode Up to 150 MB/s

DC power requirement 5 VDC 5%-100 mV ripple p-p Power

Total power consumption <1.12Watt

Dimensions (W \times H \times D) 2.74 x 0.37 x 4 in/6.98 x 0.95 x 10.2 cm

Weight 0.14 lb/65 g

Operating Temperature: 32° to 158° F (0° to 70° C)

Environmental Relative Humidity: 5% to 95%

(all conditions, non-condensing)

Maximum Wet Bulb Temperature (operating) 84° F (29° C)

Note:

For solid state disk drives, GB means 1 billion bytes. 16GB is the unformatted capacity of this drive before a portion of the drive is reserved for flash management features. Actual capacity varies by content and will be less than 15.8GB.



Technical Specifications - Hard Drives

80-GB 2.5" Solid State Drive

Capacity 80-GB

Interface Serial ATA (SATA)

Architecture Multi Level Cell (MLC) NAND Flash with wear leveling 10 channel controller

Dimensions (W x H x D) 2.74 x 0.37 x 4 in/6.98 x 0.95 x 10.2 cm

Weight 0.18 lb/80 q

Sustained Sequential Read: Up to 250 MB/s

Sustained Sequential Write: Up to 70 MB/s

Bandwidth Performance Random Read: Up to 35K IOPs

Random Write: Up to 6.6K IOPs

Latency Read: 65-ms

Write: 85-ms

DC power requirement 5 VDC 5%-100 mV ripple p-p Power

Total power consumption 0.15W (active); 0.075W (idle)

Useful Drive Life 35TB written, up to 20GB/day for 5 years

Operating Temperature: 32° to 158° F (0° to 70° C)

Relative Humidity: 5% to 95%

Environmental

Maximum Wet Bulb Temperature (operating) 84° F (29° C) (all conditions, non-condensing)

Shock: 1,500 G/0.5-ms

Note:

For solid state disk drives, GB means 1 billion bytes. 16GB is the unformatted capacity of this drive before a portion of the drive is reserved for flash management features. Actual capacity varies by content and will be less than 15.8GB.



Technical Specifications - Input/Output Devices

HP USB Standard Keyboard

Keys 104, 105, 106, 107, 109 layout

(depending upon country)

Physical characteristics

Dimensions (L x W x H)

18.0 x 6.4 x 0.98 in 45.8 x 16.3 x 2.5 cm

Weight 2 lb

0.9 kg

Operating voltage $+ 5VDC \pm 5\%$

Power consumption 50-mA maximum (with three LEDs ON)

System interface Electrical

ESD CE level 4, 15-kV air discharge

EMI – RFI Conforms to FCC rules for a Class B computing device

USB Type A plug connector

Microsoft® PC 99 – 2001 Functionally compliant

Languages 38 available

Keycaps Low-profile design

Switch actuation 55-g nominal peak force with tactile feedback

Switch life 20 million keystrokes (using Hasco modified tester)

Mechanical Switch type Contamination-resistant switch membrane

Key-leveling mechanisms For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Microsoft PC 99 –2001 Mechanically compliant

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock 40 g, six surfaces

Non-operating shock 80 g, six surfaces

Operating vibration 2-g peak acceleration

Non-operating vibration 4-g peak acceleration

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence

Environmental

Technical Specifications - Input/Output Devices

Drop (in box) 42 in (107 cm) on concrete, 16-drop sequence

Approvals UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC

Ergonomic compliance ANSI HFS 100, ISO 9241-4, and TUVGS

Keyboard Installation Guide
Kit contents

Warranty Card Safety and Comfort Guide

HP PS/2 Standard Keyboard

Keys 104, 105, 106, 107, 109 layout

(depending upon country)

50-mA maximum (with three LEDs ON)

Physical

Mechanical

characteristics

Dimensions (L x W x H) 18.0 x 6.4 x 0.98 in

45.8 x 16.3 x 2.5 cm

Weight 2 lb 0.9 kg minimum

Power consumption

Operating voltage + 5VDC ± 5%

operating voltage 570

System interface PS/2 6-pin mini din connector

System interface Electrical

ESD CE level 4, 15-kV air discharge

EMI – RFI Conforms to FCC rules for a Class B computing device

Microsoft® PC 99 – 2001 Functionally compliant

Languages 38 available

Keycaps Low-profile design

Switch actuation 55-g nominal peak force with tactile feedback

Switch life 20 million keystrokes (using Hasco modified tester)

Switch type Contamination-resistant switch membrane

Key-leveling mechanisms For all double-wide and greater-length keys

Cable length 6 ft

1.8 m

Microsoft PC 99 –2001 Mechanically compliant

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Technical Specifications - Input/Output Devices

Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock 40 g, six surfaces **Environmental**

Non-operating shock 80 g, six surfaces

Operating vibration 2-g peak acceleration

Non-operating vibration 4-g peak acceleration

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence

Drop (in box) 42 in (107 cm) on concrete, 16-drop sequence

Approvals UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC

Ergonomic compliance ANSI HFS 100, ISO 9241-4, and TUVGS

Keyboard Installation Guide
Kit contents

Warranty Card Safety and Comfort Guide

HP USB SmartCard Keyboard

characteristics

Electrical

Keys 104, 105, 106, 107, 109 layout

(depending upon country)
USB basic Smart Card keyboard

Physical Colors USB basic Smart

Colors Carbonite/Silver

18.2 x 6.3 x 1.3 in

Dimensions (H x W x D) 46.3 x 16.1 x 3.3 cm

Weight 2 lb (0.9 kg) minimum

Operating voltage $+ 5VDC \pm 5\%$

Power consumption 100-mA maximum (with four LEDs ON)

System interface USB Type A plug connector

ESD CE level 4, 15-kV air discharge

EMI - RFI Conforms to FCC rules for a Class B computing device

Microsoft PC 99 - 2001 Functionally compliant

Languages 30+ available **Keycaps** Low-profile design

KeycapsLow-profile designSwitch actuation55 g nominal peak force with tactile feedback

Switch life 20 million keystrokes (using Hasco modified tester)

Mechanical Switch type Contamination-resistant membrane

Key-leveling mechanisms For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Microsoft PC 99 - 2001 Mechanically compliant

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C)



Environmental

Technical Specifications - Input/Output Devices

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient) Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock 40 q, six surfaces

Operating vibration 2-g peak acceleration Non-operating vibration 4-g peak acceleration

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence **Drop** (in box) 42 in (107 cm) on concrete, 16-drop sequence

80 g, six surfaces

Support All ISO 7816 smart cards

Reads from and writes to all ISO7816-1, 2, 3, 4 memory and Interface

microprocessor smart cards (T=0, T=1)

Chipset **SCM STCII**

PC/SC, EMV2000, SET **Standard APIs supported**

USB Port

Short circuit detection (protects smart card and reader) **Power**

Power supply compliant with ISO7816 and EMV (5V, 60 mA)

Supports 3-V and 5-V cards

250-mA maximum draw (50 mA for the keyboard with three LEDs **Power consumption** ON and 200-mA maximum startup current using a high-current,

60-mA smart card)

SMARTCARD function

Communication

Non-operating shock

Programmable from 9,600 baud From card

89/336/CEE guideline

to 115,200 baud

From computer Up to 38,400 baud

Contact device Friction contact **Landing mechanism**

Card insertions rating Up to 100,000 insertion cycles

Interface modes SCM protocol

Automatic card insertion/removal detection

USB communications through USB port

Reader performance interface **USB** connection

Electro-magnetic standards

Europe

USA **USAFCC** part 15

HP PS/2 Optical Mouse

Dimensions 1.56 x 2.44 x 4.61 in $(H \times L \times W)$ 3.95 x 6.21 x 11.7 cm

4.44 oz Weight 126 g

> -32° to 104°F Operating temperature

> 0° to 40° C



Environmental

Electrical

Technical Specifications - Input/Output Devices

Non-operating temperature

-4° to 140°F
-20° to 60° C

Operating humidity 10% to 90%

(non condensing at ambient)

Non-operating humidity 10% to 90%

(non condensing at ambient)

Operating shock 40 g, 6 surfaces

Non-operating shock 80 g, 6 surfaces

Operating vibration 2 g peak acceleration

Non-operating vibration 4 g peak acceleration

Drop (out of box) 80 cm height onto asphalt tile over concrete or equivalent, 5-drop in

5 direction except the cable face

Operating voltage 5 VDC ± 10%

Power consumption 100mA

System consumption PS/2 mini-din connector

ESD CE level 4, 15 kV air discharge

EMI-RFI Conforms to FCC rules for a Class B computing device

Microsoft PC99 - 2001 Functionally compliant

Resolution 400 ± 20% DPI

Tracking speed 10 in/s (25.4 cm/s) maximum

Acceleration 100 in/s/s (2.54 m/s/s)

Switch actuation 61 g nominal peak force

Mechanical Switch life 3,000,000 operations (using Hasco modified tester)

Switch type Low force micro-switches

Tracking mechanism life 155 mi (250 km) at average speed of 10 in/s

Cable length 6 ft (1.8 m)

Microsoft PC99 - 2001 Mechanically compliant

Width 8 mm

Diameter 1.01 in (25.6 mm)

Maximum rotation speed 48 rats/sec

Switch type Light force micro-switch

Switch life 1 million operations

Scroll wheel

Technical Specifications - Input/Output Devices

Mechanical life Minimum 200,000 revolutions

Regulatory approvals Compliant UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC

HP USB Optical Mouse

 Dimensions
 1.5 x 4.5 x 2.5 in

 (H x L x W)
 3.8 x 11.6 x 6.3 cm

Weight 0.27 lb 0.12 kg

Cable length 72.8 in 185 cm

System requirementsMicrosoft Windows 95, 98, 2000, Me, XP and Vista

Available USB port

HP USB Laser Mouse

Scroll Wheel 24

Maximum Rotation Speed 48 rats/sec

Switch Type wheel

Switch Life Button – 3,000,000

Wheel – 1,000,000 times Tilt switch – 500,000 times

Environmental Operating Temperature

32° to 104° F 0° to 40° C

Non-operating Temperature

-4° to 140° F -20° to 60° C

Operating Humidity 10% to 90%

(non-condensing at ambient)

Non-operating Humidity 20% to 80%

(non-condensing at ambient)

Operating Shock 40 g, six surfaces

Non-operating Shock 80 g, six surfaces

Operating Vibration 2-g peak acceleration

Non-operating Vibration 4-g peak acceleration

Electrical Operating Voltage $+ 5VDC \pm 5\%$

Power Consumption



Technical Specifications - Input/Output Devices

MTBF > 150,000 hrs

ESD IEC-61000-4-2 criteria B, Contact discharge: +/- 4kV, Air

discharge: +/- 8kV

EMI-RFI FCC Class B

PC98 PC 99 Compliant

Mechanical Resolution 800dpi

Tracking Speed 25 cm/sec

Acceleration 0.5mm

Switch Actuation 0.6N (60gf)

Switch Life Button – 3,000,000

Wheel – 1,000,000 times Tilt switch – 500,000 times

Cable Length 1850mm

PC98-99 PC99 compliant

Regulatory Approvals UL60950-1, UL 94, UL 746 (A-E), UL 796

TUV/GS: EN 60950-1, EN 60825-1

FCC Class B, UL 1950, cUL, TUV GS, CE, C-tick, VCCI, BSMI, RRL



Technical Specifications - Optical Storage

HP Blu-ray Writer Drive

AMO Part Number AR482AA

Height 5.25-inch, half-height, tray-load Orientation Either horizontal or vertical

Interface type SATA

Disc capacity 50 GB DL or 25 GB standard

5.9 x 1.7 x 7.5 in **Dimensions** (W x H x D)

15.0 x 4.4 x 19.0 cm

2.0 lb Weight (max)

Disc Capacity

907g

Startup Time

DVD-ROM 8.5GB DL or 4.7GB standard 50GB DL or 25GB standard Blu-ray

Full Stroke DVD < 250 ms (seek) **Full Stroke CD** < 210 ms (seek) Blu-ray < 275 ms (seek)

(Time to drive ready from tray loading)

BD-ROM (SL/DL) 255 / 285 BD-R (SL/DL) 255 / 285 BD-RE (SL/DL) 255 / 285

DVD-ROM (SL/DL) 185 / 185

DVD-R (SL/DL) 255 / 255

> DVD-RW **25S** DVD+R (SL/DL) 255 / 255

DVD+RW **25S DVD-RAM 45S** CD-ROM **15S**

CD-ROM up to 40X

CD-ROM Read CD-RW up to 40X

8x CAV

DVD-RAM up to 5X DVD+RW up to 10X DVD-RW up to 10X DVD+R DL up to 8X

DVD-R DL up to 8X **DVD-ROM Read**

> DVD-ROM up to 16X DVD-ROM DL up to 8X DVD+R up to 12X

DVD-R up to 12X BD-ROM up to 6X BD-ROM DL up to 4.8X

Maximum Data Transfer Rates

Technical Specifications - Optical Storage

BD-R up to 6X Blu-ray

BD-R DL up to 4.8X

BD-R up to 6X

BD-RE SL/DL up to 4.8X

Source SATA DC power receptacle

5 VDC ± 5%-100 mV ripple p-p **DC Power Requirement** 12 VDC ± 5%-200 mV ripple p-p

5 VDC -1000 mA typical, 1600 mA maximum **DC Current**

12 VDC -600 mA typical, 1400 mA maximum

Temperature (operating) 41° to 122° F (5° to 50° C)

10% to 90%

Relative Humidity (operating) (all conditions

Maximum Wet Bulb non-condensing) 86° F (30° C) **Temperature** (operating)

HP SuperMulti Drive

Power

Environmental

AMO Part Number AR630AT

Height 5.25-inch, half-height, tray-load Orientation Either horizontal or vertical

Interface type Serial ATA

5.9 x 1.7 x 8.0 in **Dimensions** (W \times H \times D)

(15.0 x 4.4 x 20.3 cm)

2.6 lb Weight (max) (1.2 kg)

> Random < 120 ms typical **CD Media Read Access Full Stroke** < 200 ms typical

> Random < 130 ms typical **DVD Media Read Access Full Stroke** < 240 ms typical

CD-ROM, CD-R Read Up to 6000 KB/s (40X)

CD-RW Read Up to 4800 KB/s (32X)

Digital/Analog Up to 2400 KB/s (16X) Audio Playback

CD Media Read Transfer Digital Audio Extraction Up to 6000 KB/s (40X)

(CD-ROM, CD-R)

Digital Audio Extraction Up to 4800 KB/s (32X)

(CD-RW)

Video CD Playback Up to 2400 KB/s (16X) **DVD-ROM SL Read** Up to 21600 KB/s (16X) **DVD-ROM DL Read** Up to 10800 KB/s (8X) **DVD Video Playback** Up to 10800 KB/s (8X)

DVD Video SL Up to 21600 KB/s (16X)

(other than playback)



	Technical	Specifications - C)ptica	l Storage
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	DVD Media Read Transfer	DVD Video DL (other than playback)	Up to 10800 KB/s (8X)
		DVD-R	Up to 21600 KB/s (16X)
		DVD+R	Up to 21600 KB/s (16X)
Performance		DVD-RW	Up to 10800 KB/s (8X)
		DVD-R DL	Up to 10800 KB/s (8X)
		DVD+RW	Up to 10800 KB/s (8X)
		CD-R Write	Up to 6000 KB/s (40X)
		CD-RW	600 KB/s (4X)
	CD Media Write Transfer	CD-RW (High speed)	1500 KB/s (10X)
		CD-RW (Ultra speed)	Up to 3600 KB/s (24X)
		CD-RW (Ultra speed+)	Up to 4800 KB/s (32X)
		DVD+R	Up to 21600 KB/s (16X)
		DVD+R DL (v1.2)	Up to 16200 KB/s (12X)
		DVD+R DL (v1.1)	Up to 10800 KB/s (8X)
		DVD+RW (Volume 2 v1.0)	Up to 10800 KB/s (8X)
		DVD+RW (Volume 1 v1.3)	Up to 5400 KB/s (4X)
		DVD-R (v2.1 rev. 6.0)	Up to 16200 KB/s (12X)
	DVD Media Write Transfer	DVD-R (v2.1 rev. 4.0)	Up to 21600 KB/s (16X)
		DVD-R DL (v3.0 rev. 5.0)	Up to 10800 KB/s (8X)
		DVD-R DL (v3.0 rev. 3.0)	Up to 10800 KB/s (8X)
		DVD-RW (v1.2 rev. 3.0)	8100 KB/s (6X)
		DVD-RW (v1.2 rev. 2.0)	Up to 5400 KB/s (4X)
		DVD-RAM (v2.2 rev. 5.0)	Up to 16200 KB/s (12X)
		DVD-RAM (v2.2 rev. 2.0)	Up to 6750 KB/s (5X)
	Media	Read	Write
	CD-ROM	Yes	No
	CD-R	Yes	No
	CD-RW	Yes	No
	DVD-ROM	Yes	No
	DVD-ROM DL	Yes	No
Media Compatibility	DVD-RAM	Yes	No
	DVD+R	Yes	No
	DVD+R DL	Yes	No
	DVD+RW	Yes	No
	DVD-R	Yes	No
	DVD-RW	Yes	No
	DVD-R DL	Yes	No
	Source	SATA DC power receptacle	
	DC Dower Beguirement	5 VDC ± 5%	100 mV ripple p-p
	DC Power Requirement	12 VDC ± 5%	200 mV ripple p-p
		12 VDC ± 3/0	200 mv rippte p-p



Technical Specifications - Optical Storage

<1000 mA (typical) 5 VDC **Power Supply** 1600 mA (max.)

> 1200 mA (typical) **DC** Current **12 VDC** 2000 mA (max.)

> > **Total Drive Power** < 2.5W (Standby Mode)

SATA Power Connector, 15-pin **Rear Panel** SATA Data Connector, 7-pin

Markings to identify each connector

Temperature 41° to 122° F (operating) (5° to 50° C) Temperature -22° F to 140° F (storage) (-30° C to 60° C)

conditions **Relative Humidity** 10% to 90% non-condensing)

Maximum Wet Bulb Temperature 86° F (30° C)

0 to 10,171 ft. Altitude (0 to 3,100 meters)

HP DVD-ROM Drive

Environmental conditions (all

AMO Part Number AR629AA

Height 5.25-inch, half-height, tray-load Orientation Either horizontal or vertical

Interface type Serial ATA

5.9 x 1.7 x 8.0 in **Dimensions** (W x H x D)

(15.0 x 4.4 x 20.3 cm)

2.6 lb Weight (max) (1.2 kg)

> Random < 120 ms typical CD Media Read Access **Full Stroke** < 200 ms typical

< 130 ms typical Random **DVD Media Read Access** Full Stroke < 240 ms typical

> CD-ROM, CD-R Read Up to 6000 KB/s (40X) CD-RW Read Up to 4800 KB/s (32X)

Digital/Analog Up to 2400 KB/s (16X) Audio Playback

Up to 6000 KB/s (40X)

CD Media Read Transfer Digital Audio Extraction

(CD-ROM, CD-R)

Digital Audio Extraction

Up to 4800 KB/s (32X) (CD-RW)

Video CD Playback Up to 2400 KB/s (16X) **DVD-ROM SL Read** Up to 21600 KB/s (16X) **DVD-ROM DL Read** Up to 10800 KB/s (8X)

DVD Video Playback Up to 10800 KB/s (8X)

Performance

Technical Specifications - Optical Storage

		DVD Video SL (other than playback)	Up to 21600 KB/s (16X)
	DVD Media Read Transfer	DVD Video DL (other than playback)	Up to 10800 KB/s (8X)
		DVD-R	Up to 21600 KB/s (16X)
		DVD+R	Up to 21600 KB/s (16X)
		DVD-RW	Up to 10800 KB/s (8X)
		DVD-R DL	Up to 10800 KB/s (8X)
		DVD+RW	Up to 10800 KB/s (8X)
	Media	Read	Write
	CD-ROM	Yes	No
	CD-R	Yes	No
	CD-RW	Yes	No
	DVD-ROM	Yes	No
	DVD-ROM DL	Yes	No
Media Compatibility	DVD-RAM	Yes	No
	DVD+R	Yes	No
	DVD+R DL	Yes	No
	DVD+RW	Yes	No
	DVD-R	Yes	No
	DVD-RW	Yes	No
	DVD-R DL	Yes	No
	Source	SATA DC power receptacle	
	DC Daway Dagwiyamant	5 VDC ± 5%	100 mV ripple p-p
	DC Power Requirement	12 VDC ± 5%	200 mV ripple p-p
Power Supply		5 VDC	<1000 mA (typical) 1600 mA (max.)
	DC Current	12 VDC	1200 mA (typical) 2000 mA (max.)
		Total Drive Power (Standby Mode)	< 2.5W
Rear Panel	SATA Power Connector, 15-pin SATA Data Connector, 7-pin Markings to identify each connec	ctor	
	Temperature	41° to 122° F	
	(operating)	(5° to 50° C)	
Environmental conditions (all	Temperature (storage)	–22° F to 140° F (–30° C to 60° C)	
conditions non-condensing)	Relative Humidity	10% to 90%	
non condensing/	Maximum Wet Bulb Temperature	e 86° F (30° C)	
	Altitude	0 to 10,171 ft. (0 to 3,100 meters)	



HP Compaq 8100 Elite Series

QuickSpecs

Technical Specifications - Optical Storage



Technical Specifications - Removable Storage

HP 22-n-1 Media Card Reader plus 1394 Media Card Reader

USB 2.0 High-speed interface

USB Interface

Requires the USB cable to be connected to the internal USB 2.0 port or a USB 2.0 PCI card.

1394 Interface Two IEEE-1394a external ports; 1 IEEE-1394a internal port

(connects to the pass through cable on the media card reader)

Supports hardware ECC (Error Correction Code) function

Supports hardware CRC (Cyclic Redundancy Check) function

Supports MS 4-bit parallel transfer mode

Supports MS-PRO 4-bit parallel transfer mode

Advance protocol support Supports MS PRO-HG Duo 4-bit parallel transfer mode

Supports SD 4-bit parallel transfer mode

Supports high-speed 50Mhz SD 4-bit card (version 2.0)

Supports high-speed 52Mhz MultiMediaCard 8-bit card (version 4.2)

Supports CF v4.0 with PIO mode 6 and Ultra DMA mode

CompactFlash Type I

CompactFlash Type II

Microdrive

MultiMediaCard

Reduced Size MultiMediaCard (RS MultiMediaCard)

MultiMediaCard 4.2 (MultiMediaCard Plus, including MultiMediaCard Plus HC)

Reduced Size MultiMediaCard 4.2 (MultiMediaCard Mobile, including MultiMediaCard Mobile HC)

Secure Digital Card (SD)

Secure Digital High Capacity (SDHC)

miniSD

miniSD High Capacity
Supported media type

Micro SD (T-Flash)

Micro SD HC

Memory Stick

Memory Stick Select

Memory Stick Duo (MS Duo)



Technical Specifications - Removable Storage

Memory Stick PRO (MS PRO)

Memory Stick PRO Duo (MS PRO Duo)

Memory Stick PRO-HG Duo

MagicGate Memory Stick (MG)

MagicGate Memory Stick Duo

Picture Card

Supported media type with card adapter

Environmental

Memory Stick Micro (M2)

MultiMediaCard Micro

Test Parameters/Conditions - Power applied, unit operating on

system ±5%

nominal supply voltage.

10°C 10% R.H. = 24 hours

Operational Environmental

Extremes

10°C 90% R.H. = 24 hours 20°C 90% R.H. = 24 hours

30°C 90% R.H. = 24 hours 40°C 90% R.H. = 24 hours 50°C 90% R.H. = 24 hours 50°C 10% R.H. = 24 hours

Test Parameters/Conditions

140°F (60°C) @ 80% R.H. for 96 hours

Storage Environmental

Extremes

-22°F (-30°C) @ 20% R.H. for 48 hours

No power applied Delta °C < 1.0°C/min

Delta % R.H. < 1.5% R.H./min

USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport Specification Rev. 1.0

Approvals Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3

FCC, CE, BSMI, C-Tick, VCCI, MIC, cUL, TUV-T



Technical Specifications - Environmental Data

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- US ENERGY STAR ®
- IT ECO declaration
- EPEAT Gold where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country.

Small Form Factor

Energy Consumption (typically configured)	115 VAC	230 VAC	100 VAC
Normal Operation	39.787 W	39.547 W	39.865 W
Sleep (Energy Star low power mode)	3.2283 W	3.4659 W	3.2186 W
Off	1.0477 W	1.2128 W	1.0345 W
Heat Dissipation (typically configured)*	115 VAC	230 VAC	100 VAC
Normal Operation	136 BTU/hr	135 BTU/hr	136 BTU/hr
Sleep	11 BTU/hr	12 BTU/hr	11 BTU/hr
Off	4 BTU/hr	4 BTU/hr	4 BTU/hr

^{*} Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions

(in accordance with ISO 7779 and ISO 9296)

System Fan Off	Sound Power	Sound Pressure
	(LWAd, bels)	(LpAm, decibels)
Idle	3.7	27
Fixed Disk	3.7	27
(random writes)		

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight

Battery Size

CR2032 (coin cell)

Battery Type

Lithium

Additional Information

This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2002/95/EC.

This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.

This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).



Technical Specifications - Environmental Data

This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country.

Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.

This product contains 0% post consumer recycled plastic (by wt.)

This product is 95.1% recyclable when properly disposed of at end of life.

External Corrugated Carton – 1700 g

Internal EPE — Expanded Polyethylene — 198 g
Polyethylene low density foam — 160 g

The Corrugated Carton packaging material is made from 100% recycled content.

The EPE – Expanded Polyethylene packaging material is made from 100% recycled content The Polyethylene low density foam packaging material is made from 100% recycled content

Convertible Minitower

Packaging Materials

Energy Consumption (typically configured)	115 VAC	230 VAC	100 VAC
Normal Operation	46.9450 W	47.0125 W	46.5123 W
Sleep (Energy Star low power mode)	3.7745 W	3.7250 W	3.6882 W
Off	0.7562 W	0.8895 W	0.7751 W
Heat Dissipation (typically configured)*	115 VAC	230 VAC	100 VAC
Normal Operation	161 BTU/hr	161 BTU/hr	159 BTU/hr
Sleep	13 BTU/hr	13 BTU/hr	13 BTU/hr
Off	3 BTU/hr	3 BTU/hr	3 BTU/hr

^{*} Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.



Technical Specifications - Environmental Data

Declared Noise Emissions

(in accordance with ISO 7779 and ISO 9296)

System Fan Off	Sound Power (LWAd, bels)	Sound Pressure (LpAm, decibels)	
Idle	3.8	21	
Fixed Disk	3.8	21	

(random writes)

Batteries This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight:

Battery Size CR2032 (coin cell)

Li-lon

Additional Information

Battery type

This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2002/95/EC.

This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.

This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).

This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country.

Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.

This product contains 0% post consumer recycled plastic (by wt.)

This product is 90% recyclable when properly disposed of at end of life.

External Corrugated 2550 g

Internal Polyethylene high density 160 g

The corrugated packaging material is made from 37% recycled content. The Polyethylene high

density packaging material is made from 100% recycled content.

All Models

Packaging Materials

Reduction in Hazardous Substances (RoHS) Compliance

Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at:



Material Usage

Packaging

Technical Specifications - Environmental Data

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
- Nickel finishes that release greater than 0.5 micro-grams/cm²/week, measured according to EN 1811:1998, are not used on any product surface designed to be frequently handled or touched by users.

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

End-of-life Management and Recycling

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

For more information about HP's commitment to the environment: Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

(hp

Technical Specifications - Environmental Data

Hewlett-Packard Corporate Environmental Information **Eco-label certifications**

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/

ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/

envmanagement.html

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